

Patent Claims

1. A method for making contact between at least one
5 one application, with
 - contact surfaces being provided on a side of the
module which is intended to make contact with
the application, and
 - contact surfaces which can interact with the
10 contact surfaces of the module being provided on
a side of the application which is intended to
make contact with the module, and
 - a connection being produced between the
15 respective contact surfaces of the module and
the application.
2. The method as claimed in claim 1,
characterized
20 in that a detachable connection is provided
between the respective contact surfaces by means
of a mechanical apparatus which allows the module
to be replaced by pushing it in and out.
3. The method as claimed in claim 1,
25 characterized
in that a firm connection is provided between the
respective contact surfaces.
4. The method as claimed in claim 3,
30 characterized
in that the respective contact surfaces are
soldered or pressed together.
5. The method as claimed in one of the preceding
35 claims,
characterized

- 9 -

in that the respective contact surfaces are arranged in the form of a grid.

5 6. The method as claimed in one of the preceding claims,
characterized

in that the contact surfaces are formed by a metallic coating with a low electrical and/or thermal resistance.

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7. A combination, having a module for wire-free radio standards and having an application, with the module having contact surfaces on a side which is intended to make contact with the application, and
15 the application having contact surfaces on a side which is intended to make contact with the module, which latter contact surfaces can interact with the contact surfaces of the module and can make contact with them.

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8. The combination as claimed in claim 7,
characterized
in that the respective contact surfaces can be detachably connected to one another.

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9. The combination as claimed in claim 7,
characterized
in that the respective contact surfaces can be permanently connected to one another.

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10. The combination as claimed in claim 9,
characterized
in that the respective contact surfaces can be soldered to one another.

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11. The combination as claimed in one of claims 7 to 10,

characterized

in that the respective contact surfaces are arranged in the form of a grid.

New Patent Claims

1. A method for making contact between at least one module for wire-free radio standards and at least one application, with
- 5 - contact surfaces being provided on a side of the module which is intended to make contact with the application, and
- 10 - contact surfaces which can interact with the contact surfaces of the module being provided on a side of the application which is intended to make contact with the module, and
- 15 - a connection being produced between the respective contact surfaces of the module and the application, with at least one of the contact surfaces being formed by a metallic coating with a low electrical and thermal resistance.
- 20 6. A combination, having a module for wire-free radio standards and having an application, with the module having contact surfaces on a side which is intended to make contact with the application, and the application having contact surfaces on a side
- 25 which is intended to make contact with the module, which latter contact surfaces can interact with the contact surfaces of the module and can make contact with them, with at least one of the contact surfaces being formed by a metallic
- 30 coating with a low electrical and thermal resistance.